

## IRFH5006TR2PBF-VB Datasheet

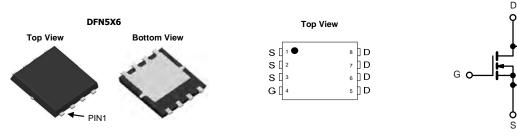
### N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>		
60	0.003 at V <sub>GS</sub> = 10 V	100		
	0.005 at V <sub>GS</sub> = 4.5 V	85		

#### **FEATURES**

- 175 °C Junction Temperature
  TrenchFET<sup>®</sup> Power MOSFET
- Material categorization:





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> =	= 25 °C, unless othe	rwise noted)			
Parameter	Symbol	Limit	Unit		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	1-	100		
	T <sub>C</sub> = 100 °C	- I <sub>D</sub> —	85 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	100	А		
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	80 <sup>a</sup>			
Avalanche Current	I <sub>AS</sub>	70			
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	125	mJ	
Maximum Dawar Dissinction	T <sub>C</sub> = 25 °C	Pn –	136	- w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Manimum lugation to Amhienta	t ≤ 10 sec	R <sub>thJA</sub>	15	18	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		40	50		
Maximum Junction-to-Case	·	R <sub>thJC</sub>	0.85	1.1		
Notes:						

a. Package limited.

c.  $t \le 10$  s.

b. Surface mounted on 1" x 1" FR4 board.

<b>B</b> <sup>®</sup> VBsemi
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SPECIFICATIONS (T <sub>J</sub> = 25 Parameter	Symbol	Test Conditions	Min.	Turn 2	Max.	Unit	
	Symbol	Test conditions	win.	Typ. <sup>a</sup>	Wax.	Unit	
Static	V	$V_{1} = 0 V_{1} = 250 \mu \Lambda$	<u> </u>				
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1	2	3		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50		
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	60			А	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.003			
	D	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$		0.008		Ω	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.010			
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.005			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic	<u> </u>			<u> </u>			
Input Capacitance	C <sub>iss</sub>			2650			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz$		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	Qg			47	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 30 V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A		10		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> = 30 V, R <sub>I</sub> = 0.6 Ω		15	25	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 2.5 \Omega$		35	50		
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)	·	·	•	- -	
Pulsed Current	I <sub>SM</sub>				60	A	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		45	100	ns	

#### **SPECIFICATIONS** (T<sub>1</sub> = 25 °C, unless otherwise noted)

Notes:

a. For design aid only; not subject to production testing.

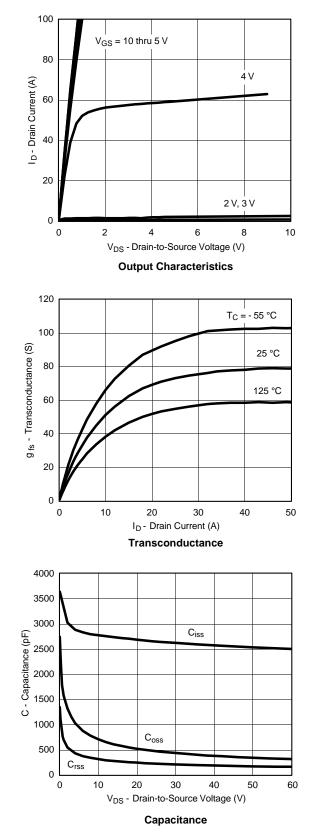
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

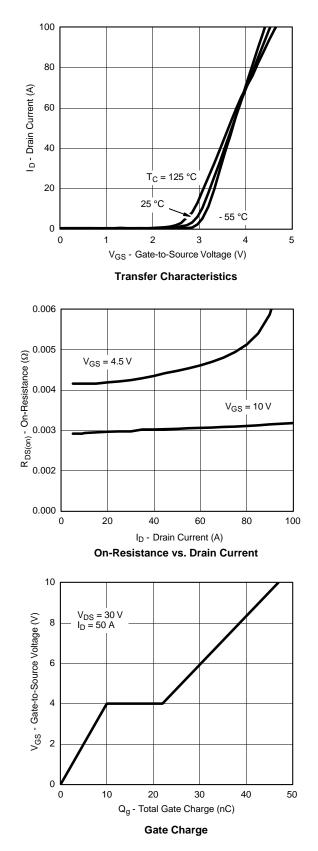
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



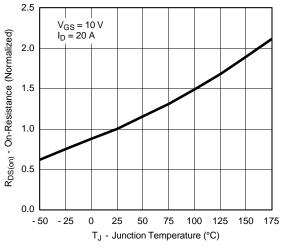
#### TYPICAL CHARACTERISTICS (25 °C unless noted)



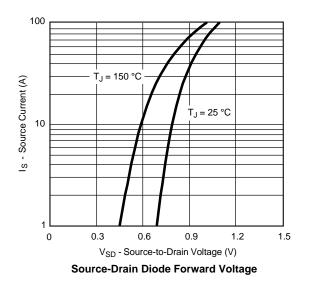




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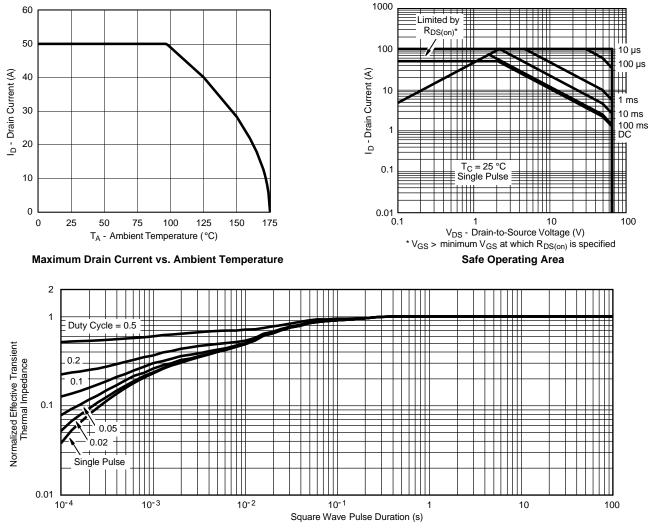
**On-Resistance vs. Junction Temperature** 



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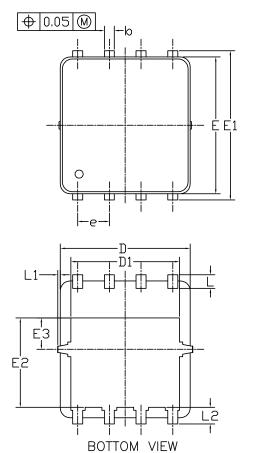


#### **THERMAL RATINGS**

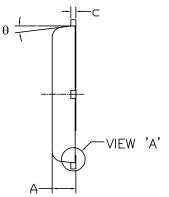


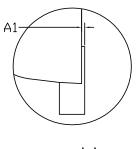
Normalized Thermal Transient Impedance, Junction-to-Case





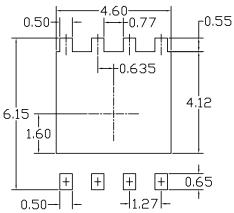
DFN5x6\_8L\_EP1\_P PACKAGE OUTLIN





<u>VIEW 'A'</u> (SCALE 5:1)

RECOMMENDED LAND PATTERN



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
SIMBOLS	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.85	0.95	1.00	0.033	0.037	0.039
A1	0.00		0.05	0.000		0.002
b	0.30	0.40	0.50	0.012	0.016	0.020
с	0.15	0.20	0.25	0.006	0.008	0.010
D	5.10	5.20	5.30	0.201	0.205	0.209
D1	4.25	4.35	4.45	0.167	0.171	0.175
E	5.45	5.55	5.65	0.215	0.219	0.222
E1	5.95	6.05	6.15	0.234	0.238	0.242
E2	3.525	3.625	3.725	0.139	0.143	0.147
E3	1.175	1.275	1.375	0.046	0.050	0.054
e	1.27 BSC			0.050 BSC		
L	0.45	0.55	0.65	0.018	0.022	0.026
L1	0		0.15	0		0.006
L2	0.68 REF			0.027 REF		
θ	0°		10°	0°		10°

NOTE

UNIT: mm

 PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
 CONTROLLING DIMENSION IS MILLIMETER.

CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.



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